

Product Compliance Declaration

Please see www.molex.com for the most up-to-date information.

Contact Information

Name Molex Product Compliance E-Mail Product.Compliance@molex.com

Part Information

Part Name MGrid Shrd Hdr SMT/Peg&cap 2.5SnLF 12Ckt

Product Composition

Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
MGrid Shrd Hdr SMT/Peg∩ 2.5SnLF 12Ckt	Assembly		100	0.578956
2MM MGrid Hsg DR Shrd Wafer w/Peg 12Ckt	Component		63.9081	0.37
LCP-GF30	Material		63.9081	0.37
Carbon black	Substance	1333-86-4	0.3195	0.00185
LCP	Substance		43.4575	0.2516
Further Additives, not to declare	Substance	system	0.9586	0.00555
GF-Fibre	Substance		19.1724	0.111
0.5mm SqPin Bando w/Swage Brs 2.5SnLF	Assembly		36.0919	0.208956
0.5mm SqPin Bando w/Swage Brs Unpl	Component		35.0286	0.2028
Cartridge Brass 70% Unplated	Material		35.0286	0.2028
Copper	Substance	7440-50-8	24.52	0.14196
Zinc (metal)	Substance	7440-66-6	10.5086	0.06084
Nickel Plating	Material		0.4009	0.002321

Form Rev - F

Limitation of this Product Compliance Declaration: This declaration is based on the state of knowledge and belief of Molex as of the date that it is provided. Molex bases its knowledge and belief on information provided by numerous sources, including third parties, and in certain circumstances laboratory test results. Molex has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and substances. Molex represents that to the best of its knowledge that the information provided in this declaration is accurate. Molex's sole liability shall be to either replace the product or refund the purchase price of the product if it does not meet the requirement of this declaration.

Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
Nickel	Substance	7440-02-0	0.4008	0.002321
Further Additives, not to declare	Substance	system	4E-05	2E-07
Tin Plating	Material		0.6624	0.003835
Tin	Substance	7440-31-5	0.6624	0.003835

ROHS Declaration Information

Regulatory Revision EU 2015/863

Compliance Status Compliant

Contained Substances Exceeding Threshold

None

Exemptions

None

REACH-SVHC Declaration Information

Regulatory Revision D(2021)4569-DC (8 July 2021)

Contained Substances Exceeding Threshold

None

GADSL Declaration Information

Regulatory Revision GADSL imported from IMDS

Contained Substances Exceeding Threshold

Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
Lead	Cartridge Brass 70% (CA260)	*Note	350	Yes
Lead	e-plate Sn (electrodeposited Tin Coatings, bright and matt)	*Note	500	Yes
nickel powder [particle diameter < 1 mm]	Ep-Ni	*Note	997,500	Yes

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Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
copper	Cartridge Brass 70% (CA260)	*Note	700,000	Yes

^{*}Note: For GADSL substance declarable/prohibited threshold values, please reference http://www.gadsl.org/

Exemptions

Part Name	Exemption
Cartridge Brass 70% (CA260)	44 Concentration within acceptable GADSL limits
e-plate Sn (electrodeposited Tin Coatings, bright and matt)	44 Concentration within acceptable GADSL limits
Ep-Ni	33 Other application (Surface not routinely touched or nickel release rate < 0.5µg/cm2/week)

HFLH Declaration Information

Regulatory Revision IEC 61249-2-21

Contained Substances Exceeding Threshold

None

China ROHS Declaration Information

Part Number	1511181462							
Part Name	MGrid Shrd Hdr SMT/Peg∩ 2.5SnLF 12Ckt	(e)						
Part Information	on			Ha	zardous S	Substance	s	
Components			Lead	Mercury	Cadmium	Hex. Chromium	PBB	PBDE
MGrid Shrd H	Hdr SMT/Peg∩ 2.5SnLF 12Ckt		0	0	0	0	0	0
2MM MGrid H	Hsg DR Shrd Wafer w/Peg 12Ckt		0	0	0	0	0	0
0.5mm SqPir	n Bando w/Swage Brs 2.5SnLF		0	0	0	0	0	0
0.5mm SqPir	n Bando w/Swage Brs Unpl		0	0	0	0	0	0

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Additional Information

Annex XVII to REACH (76/769/EEC)	Compliant
Regulation (EU) 2019/1021 (POP)	Compliant

Process Information

Component Plating / Surface Finish	MSn-Ni
Termination Base Alloy	Brass
Solder Alloy	N/A
Process Capability	REFLOW
Maximum Exposure Time (seconds)	010
Maximum Process Temperature (C)	260
Maximum Cycles at Reflow Temperature	001
J-STD-020 Moisture Sensitivity Level	N/A

Nov 11, 2021